



N THE CLAIMS

1. **(Previously Presented)** A single circuit board comprising a base member, an interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the interconnect layer, and a dielectric layer covering a part of the interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the interconnect layer and the edge of the electrically-floating conductive layer, wherein the interconnect layer comprises a top interconnect layer on a top surface of the base member and a bottom interconnect layer on a bottom surface of the base member and the electrically-floating conductive layer includes a top electrically-floating conductive layer on the top surface of the base member and a bottom electrically-floating conductive layer on the bottom surface of the base member.

2. **(Canceled).**

3. **(Currently Amended)** The circuit board as defined in claim 1, wherein ~~a volume of the top interconnect layer and the top electrically-floating conductive layer have a total volume which is equal to a total volume of the bottom interconnect layer are substantially equal.~~ and the bottom electrically-floating conductive layer.

4. **(Withdrawn)** The circuit board as defined in claim 1, wherein the interconnect layer includes patterns having a larger width.

5. **(Withdrawn)** A circuit board comprising a base member, an first interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the first interconnect layer, and a dielectric layer covering a part of the first interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the first interconnect layer and the edge of the electrically-floating conductive layer, and a second interconnect layer formed on the dielectric layer.

6. **(Withdrawn)** The circuit board as defined in claim 5, wherein the interconnect layer includes patterns having a larger width.

7. **(Withdrawn)** A circuit board comprising a base member, an interconnect layer formed on a part of the base member, an electrically-floating conductive layer formed on a substantially remaining part of the base member and having an edge adjacent to an edge of the interconnect layer, a dielectric layer covering a part of the interconnect layer and an entire surface of the electrically-floating conductive layer and filling a gap between the edge of the interconnect layer and the edge of the electrically-floating conductive layer, and a die disposed on the dielectric layer.

8. **(Withdrawn)** The circuit board as defined in claim 7, wherein the interconnect layer includes patterns having a larger width.